



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Device connector, front mounting - CA-09S1N122S00 - 1619973

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Device connector for front wall, straight, shielded: yes, SPEEDCON locking, M23, Number of positions: 8+1, Type of contact: Socket, Solder connection, Flat gasket, 4x Ø3.2, Flange dimensions: 25 mm x 25 mm

The figure shows the 6-pos. product version



Key Commercial Data

Packing unit	1 pc
Weight per Piece (excluding packing)	60.0 g
Custom tariff number	85366990
Country of origin	Germany

Technical data

Temperature range

Ambient temperature (operation)	-40 °C ... 125 °C
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Data of the insulating body

Coding	N
Insulator material	PBT
Contact material	CuZn
Contact surface material	Ni/Au
Contact connection method	Solder connection
Type of contacts	Socket
Number of positions	9
Contact diameter of power contacts	2 mm
Litz wire cross section of power contacts min.	0.08 mm²
Litz wire cross section of power contacts max.	2.5 mm²
Nominal current per power contact at 25°C	20 A
Nominal voltage, power contact	300 V

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Technical data

Data of the insulating body

Contact diameter of signal contacts	1 mm
Litz wire cross section of signal contacts min.	0.08 mm ²
Litz wire cross section of signal contacts max.	1 mm ²
Nominal current per signal contact at 25°C	8 A
Nominal voltage, signal contact	300 V
Overvoltage category	II
Degree of pollution	3

Housing data

Housing material	CuZn
Flange dimensions	25 mm x 25 mm
Type of locking	SPEEDCON locking
Degree of protection (when plugged in)	IP67
Thread type	M23

Classifications

eCl@ss

eCl@ss 4.0	272607xx
eCl@ss 4.1	27260701
eCl@ss 5.0	27143424
eCl@ss 5.1	27143424
eCl@ss 6.0	27143424
eCl@ss 7.0	27440209
eCl@ss 8.0	27440103

ETIM

ETIM 3.0	EC001121
ETIM 4.0	EC002635
ETIM 5.0	EC002061

UNSPSC

UNSPSC 6.01	43172015
UNSPSC 7.0901	43201404
UNSPSC 11	43172015
UNSPSC 12.01	43201404
UNSPSC 13.2	43201404

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Approvals

Approvals

Approvals

UL Recognized / cUL Recognized / EAC / cULus Recognized

Ex Approvals

Approvals submitted

Approval details

UL Recognized 	
mm²/AWG/kcmil	18
Nominal current I _N	8 A
Nominal voltage U _N	300 V

cUL Recognized 	
mm²/AWG/kcmil	18
Nominal current I _N	6 A
Nominal voltage U _N	300 V

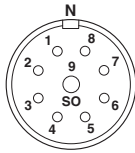
EAC

cULus Recognized 
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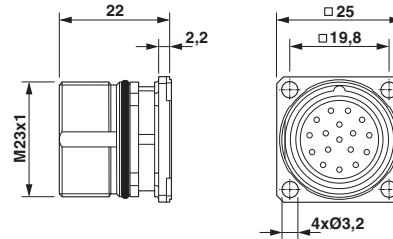
Drawings

Device connector, front mounting - CA-09S1N122S00 - 1619973

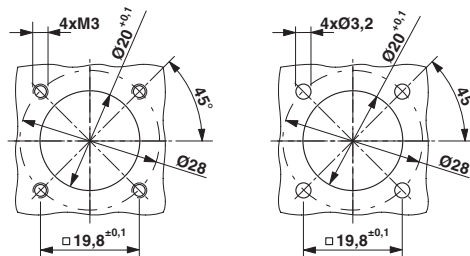
Schematic diagram



Dimensional drawing



Dimensional drawing



Installation dimensions